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## 1988

### Development of 208-pin QFP packages with two internal lead-frame (LF) layers

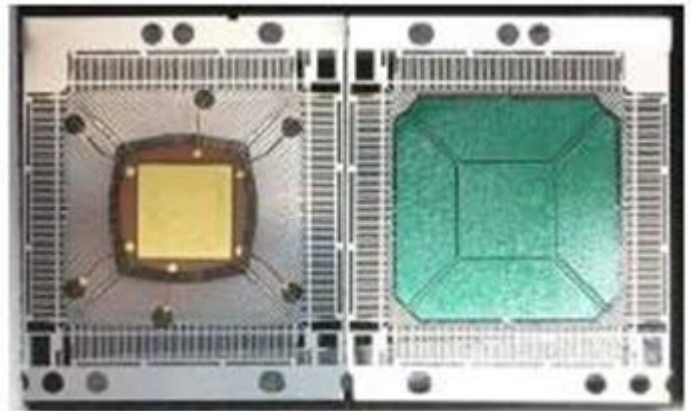
~ Packaging ~

Around 1989, Hitachi developed a 2-layered structured 208-pin QFP with a body size of 28 mm square (28×28) that has a ground layer on the inner lead portion.

By making the lead frame in two layers, the inductance component accompanying the larger number of terminals was reduced.

A copper foil patterned on a polyimide substrate was bonded to 42-alloy lead frame with a heat resistant resin. This pattern and the 42 alloy LF were electrically connected by Au wire bonding in the wire bonding process of the LSI.

This package was applied to ASIC for high-speed signal processing in main frame computer and so on.



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